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## METHOD OF CONNECTION SEMICONDUCTOR INTEGRATED CIRCUIT ELEMENT

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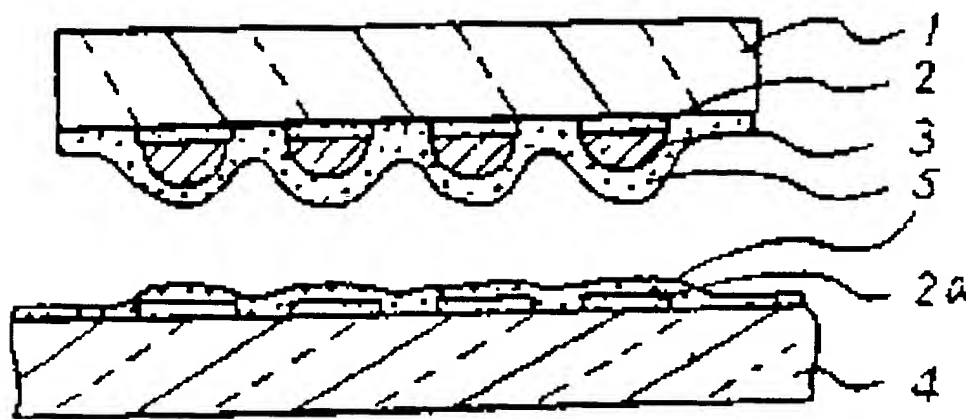
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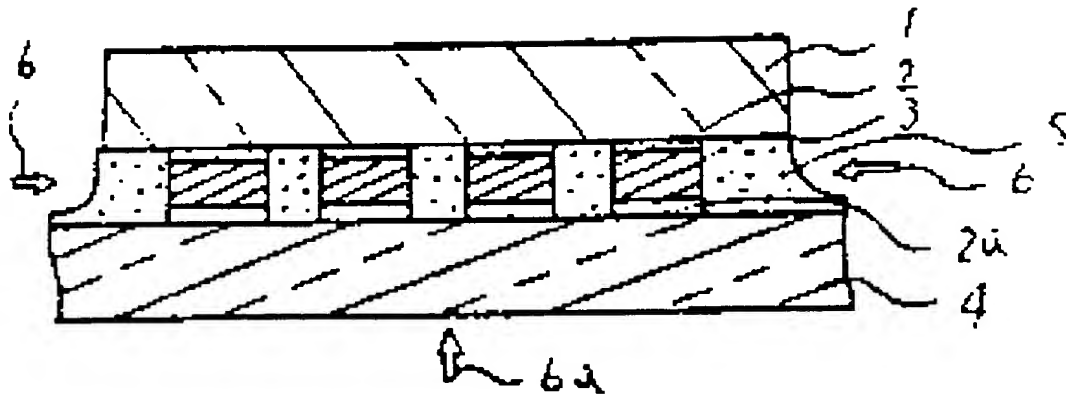
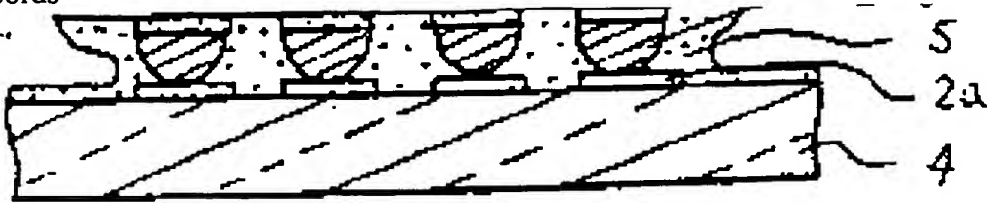
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## ABSTRACT

**PURPOSE:** To enable an IC chip to be connected without giving bad influence to ICs with improved reproducibility irradiating ultraviolet rays to a part which is connected by pressing an electrode pad and an electrode terminal and the connecting them by a melted solder and then curing ultraviolet ray curing region which are coated previously.

**CONSTITUTION:** An ultra-violet ray curing resin 5 is applied to an IC chip 1 including an electrode pad 2 to seal a soldering bump 3 or the ultra-violet ray curing region 5 is applied to an electrode terminal 2a which is formed on a printed-wiring board 4. Then, the IC chip 1 is placed on the printed-wiring board 4, an weight is placed and press for is applied to, heating is made from the IC chip 1 side, solder is reflow, and connection is made. Then, ultra- violet ra are irradiated to a high-voltage mercury lamp in the direction indicated by an arrow 6. The IC chip 1 and the printed-wiring board 4 are adhered and fixed, and at the same time the soldering connection part is fixed. Thus, it becomes possible to perform soldering connection without using any flux, fix and at the same time protect the connection part with resin easily and obtain a high-concentration fine connection with improved reliability.





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